



BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	0.062"
Board overall dimensions:	3.550" x 3.982"		
Min track/spacing:	0.006" / 0.006"	Min hole diameter:	10.00 mils
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	Yes, Bevelled, 30 degrees.		

Layer Name	Type	Material	Finished Thickness (mils)	Base Thickness (mils)	Construction Details
F.Mask	Top Solder Mask		0.5 mils	0.5 mils	
F.Cu	copper		1.45 mils	0.35 mils (0.25oz)	1.1 mils plate thickness
Dielectric 1	prepreg	N7000-2HT	4.096 mils	4.6 mils	2x106
In1.Cu	copper		1.4 mils		
Dielectric 2	core	N7000-2HT	5 mils	5 mils (1oz/1oz core)	1x2113+1x106
In2.Cu	copper		1.4 mils		
Dielectric 3	prepreg	N7000-2HT	6.932 mils	8.5 mils	1x106+1x1080+1x106
In3.Cu	copper		1.4 mils		
Dielectric 4	core	N7000-2HT	16 mils	16 mils (1oz/1oz core)	2x7628+1x1080
In4.Cu	copper		1.4 mils		
Dielectric 5	prepreg	N7000-2HT	6.932 mils	8.5 mils	1x106+1x1080+1x106
In5.Cu	copper		1.4 mils		
Dielectric 6	core	N7000-2HT	5 mils	5 mils (1oz/1oz core)	1x2113+1x106
In6.Cu	copper		1.4 mils		
Dielectric 7	prepreg	N7000-2HT	4.096 mils	4.6 mils	2x106
B.Cu	copper		1.45 mils	0.35 mils (0.25oz)	1.1 mils plate thickness
B.Mask	Bottom Solder Mask		0.5 mils	0.5 mils	

FAB NOTES:

1. IPC-6012E Class 2
2. Matte Green soldermask, White silkscreen.
3. Fabricate on Nelco N7000-2HT
4. 1oz outer, 1oz inner copper.
5. Bevel edge connector 30 degrees minimum.
6. Fill all vias with non-conductive material.
7. Board target thickness shall be 0.062"
8. Hard gold plating on finger thickness shall be 1"U

ASSEMBLY NOTES:

1. J-STD-001G Class 2
2. BOM provided with submitted files shall be the controlling document for component information.
3. Do not apply solder to pads of DNP components
4. Stake components specified in BOM with 3M 2216
5. Conformal Coat with Arathane 5750:

Ensure coating does not prevent electrical contact with connectors and mounting holes.